AMENDMENT TO THE CLAIMS:

1. (Currently amended) A method of manufacturing boards, the method comprising steps of:

laminating a metal foil on one face of a prepreg sheet;

placing a mold-releasing sheet on another face of the prepreg sheet;

heating and pressing a given place of the prepreg sheet and the metal foil via the mold-releasing sheet by a partial heat and press means, after the placing step;

peeling off the mold-releasing sheet, after heating and pressing the given place, and

heating and pressing an entire face of the prepreg sheet and the metal foil, after the peeling off step,

wherein, the heating and pressing the given place are performed at a temperature higher ~~not lower~~ than a softening point of a resin impregnated into the prepreg sheet so that the resin is kept in stage-B status, while the temperature and pressure of the pressing are set so that the resin is not hardened and not pushed out of the prepreg sheet at the given place ~~allows the resin to be kept in stage-B status~~.

2. (Currently amended) A method of manufacturing boards comprising steps of:

laminating a first metal foil on one face of a first prepreg sheet;

placing a mold-releasing sheet on another face of the prepreg sheet;

heating and pressing a first given place of the first prepreg sheet and the first metal foil via the mold-releasing sheet by a partial heat and press means;

peeling off the mold-releasing sheet after heating and pressing the first given place;

laminating a board having a circuit pattern on the another face of the first prepreg sheet, after the peeling off step;

heating and pressing a second given place of the first prepreg sheet and the board, after laminating the board;

laminating a second prepreg sheet on the board, after heating and pressing the second given place;

heating and pressing a third given place of the second prepreg sheet and the board, after laminating the second prepreg sheet;

laminating a second metal foil on the second prepreg sheet, after heating and pressing the third given place;

heating and pressing a fourth given place of the second metal foil and the second prepreg sheet; and

heating and pressing an entire face of the first prepreg sheet, the first metal foil, the board, the second prepreg sheet, and the second metal foil, after heating and pressing the fourth given place,

wherein the heating and pressing the first given place to fourth given place [[is]] are performed at a temperature higher ~~not lower~~ than a softening point of a resin impregnated into the first and the second prepreg sheet so that the resin is kept in stage-B status, while the temperature and pressure of the pressing are set so that the resin is not hardened and not pushed out of the first and the second prepreg sheet at the first given place to fourth given place ~~allows the resin to be kept in stage-B status~~.

3. (Cancelled)

4. (Previously presented) The manufacturing method as defined in claim 2, wherein the board having a circuit pattern is a composite of thermosetting resin and one of woven fiber or non-woven fiber.

5-6. (Cancelled)

7. (Previously presented) The manufacturing method as defined in claim 1 or claim 2, wherein the peeling off of the mold-releasing sheet includes peeling off the sheet from one end of the sheet toward another end.

8-28. (Cancelled)